

SNS COLLEGE OF TECHNOLOGY

Coimbatore-35

An Autonomous Institution

Accredited by NBA – AICTE and Accredited by NAAC – UGC with ‘A+’ Grade
Approved by AICTE, New Delhi & Affiliated to Anna University, Chennai

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

COURSE CODE & NAME: 19ECB302 VLSI DESIGN

III YEAR/V SEMESTER

UNIT 1- MOS TRANSISTOR PRINCIPLE

**TOPIC 2- BASIC MOS TRANSISTOR ACTION &
CMOS FABRICATION P-WELL PROCESS**



OUTLINE

- Introduction & levels of integration- Moore's law
- Design Abstraction Levels
- Why the name MOS?
- Two mode transistor action
- Activity
- Enhancement mode, Depletion mode
- P-well process with different masking levels
- CMOS P-well Inverter
- Summary

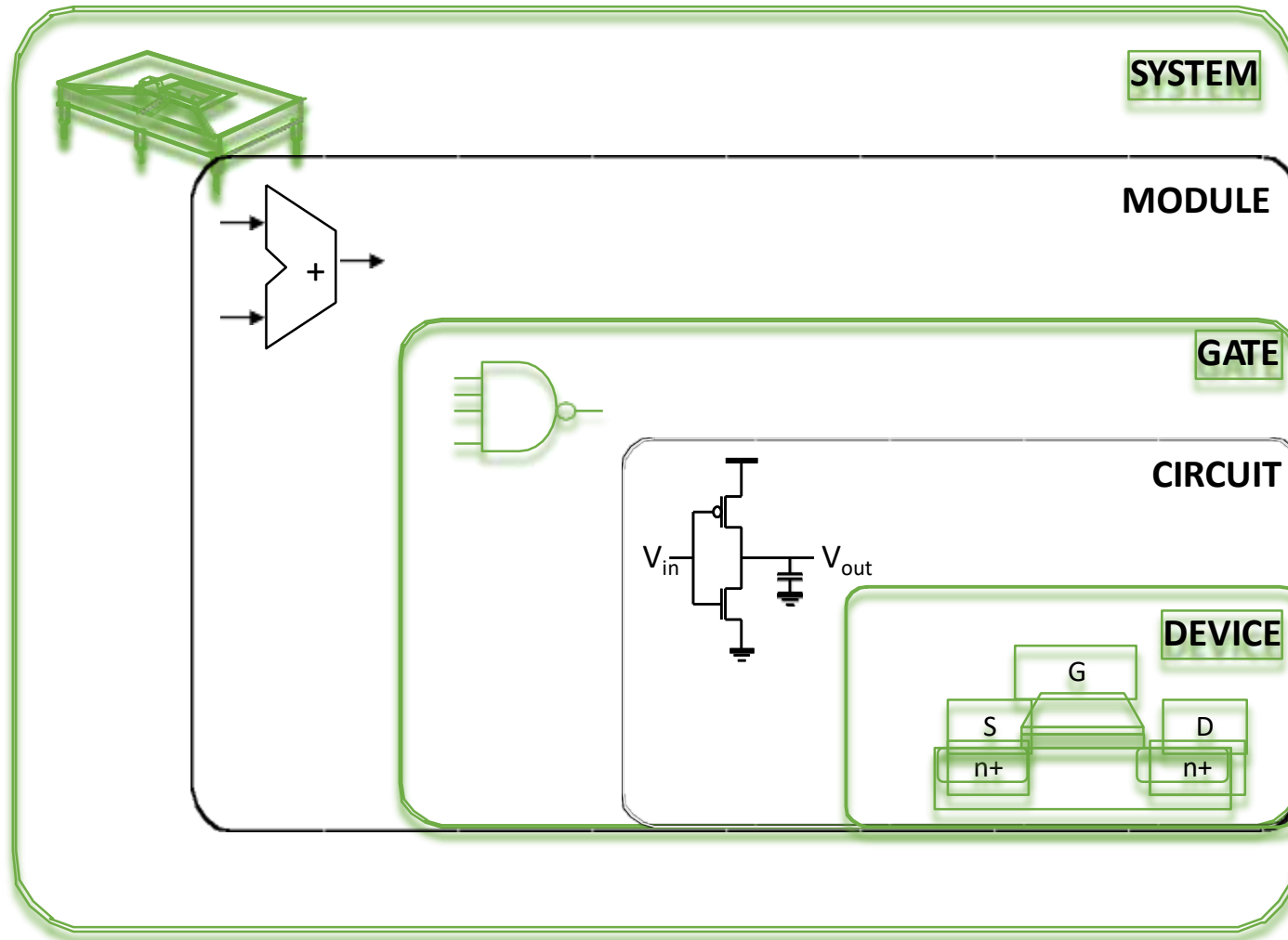


LEVELS OF INTEGRATION

| Integration | Transistors | Examples |
|-------------|----------------------|---|
| SSI | 10-100 | Logic gates |
| MSI | 100-1000 | counters |
| LSI | 1000-20000 | 8-bit chip |
| VLSI | 20000-1000000 | 16 & 32 bit up |
| ULSI | 1000000- 10000000 | Special processors, virtual reality machines, smart sensors |



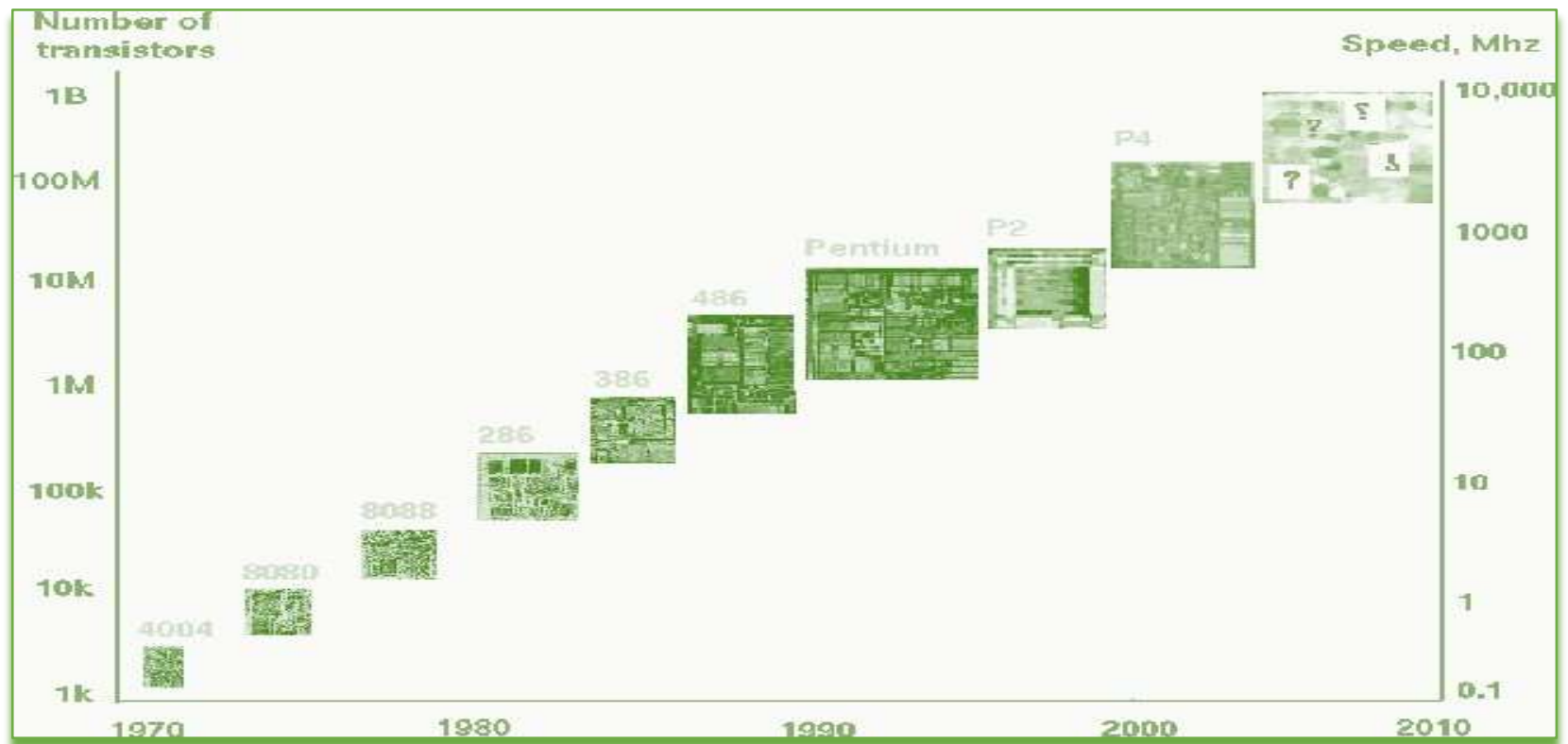
DESIGN ABSTRACTION LEVELS





MOORE'S LAW

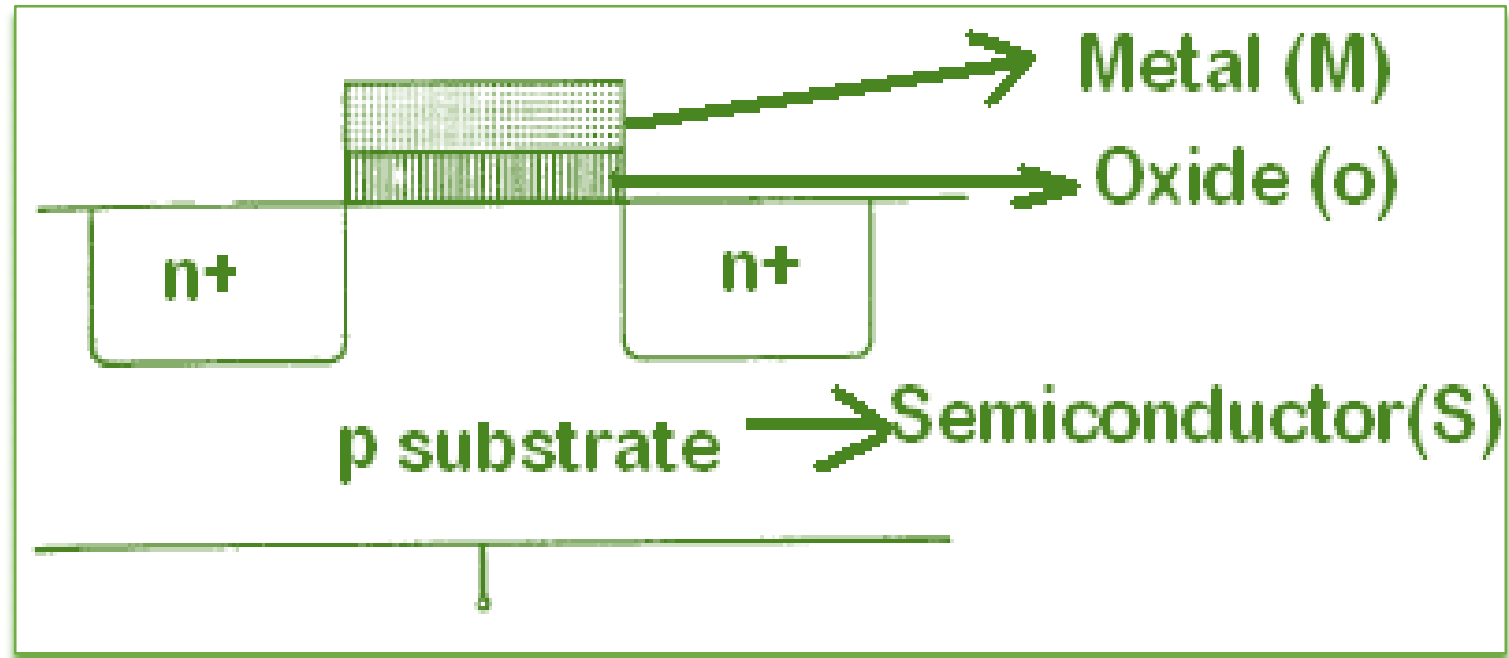
—The number of transistors embedded on the chip doubles after every one and a half years.”





WHY THE NAME MOS?

The structure consists of a layer of Metal (gate), a layer of oxide (SiO_2) and a layer of semiconductor





TWO MODE TRANSISTOR ACTION

In **Enhancement mode transistor channel** $\rightarrow +V_g$ **NMOS and PMOS enhancement transistors.**

In **Depletion mode transistor channel** $\rightarrow -V_g$
NMOS depletion mode transistors.

Example: Water tap







ACTIVITY

SOLVE IF YOU CAN

| | | | |
|----|---|---|----|
| 3 | 2 | = | 7 |
| 5 | 4 | = | 23 |
| 7 | 6 | = | 47 |
| 9 | 8 | = | 79 |
| 10 | 9 | = | ? |

 +  +  = **60**

 +  +  = **26**

 +  +  = **15**

 +  ×  = **???**



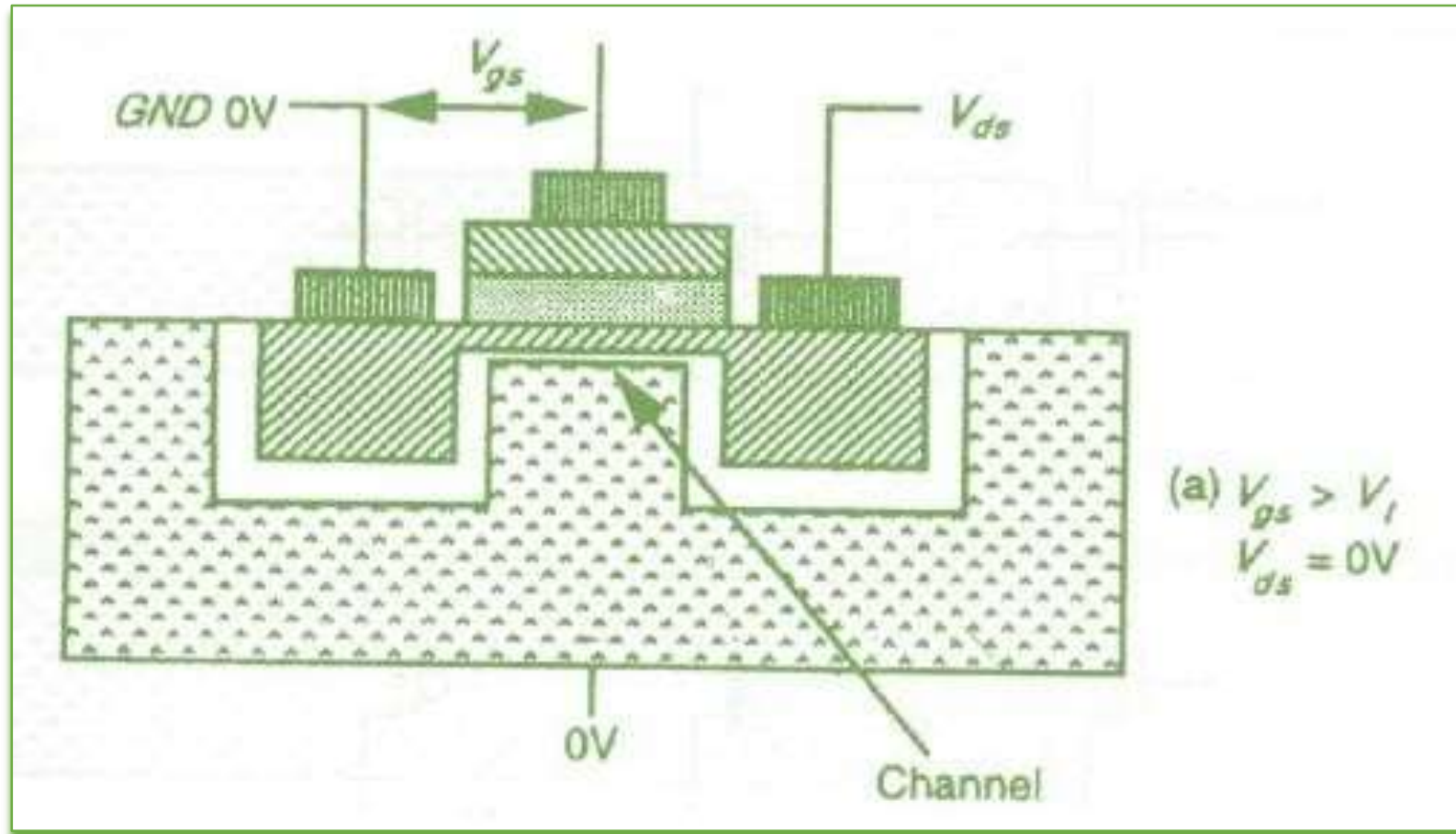
ENHANCEMENT MODE, DEPLETION MODE TRANSISTOR ACTION

| Mode transistor | Gate Voltage | Channel | ON/OFF |
|-------------------|----------------|-----------|---------------------------------------|
| N-MOS-enhancement | Positive | Electrons | ON |
| P-MOS-enhancement | Negative | Holes | ON, $V_t=0.2$ $V_{dd}=1$ or 5 V, |
| N-MOS - depletion | $-V$ b/w G & S | implanted | ON, $V_{gs}=0$ |

$\mu_n = 2.5\mu_p \rightarrow$ nMOS is speed (pMOS is more R')
 $V_{td} < -0.8 V_{dd}$

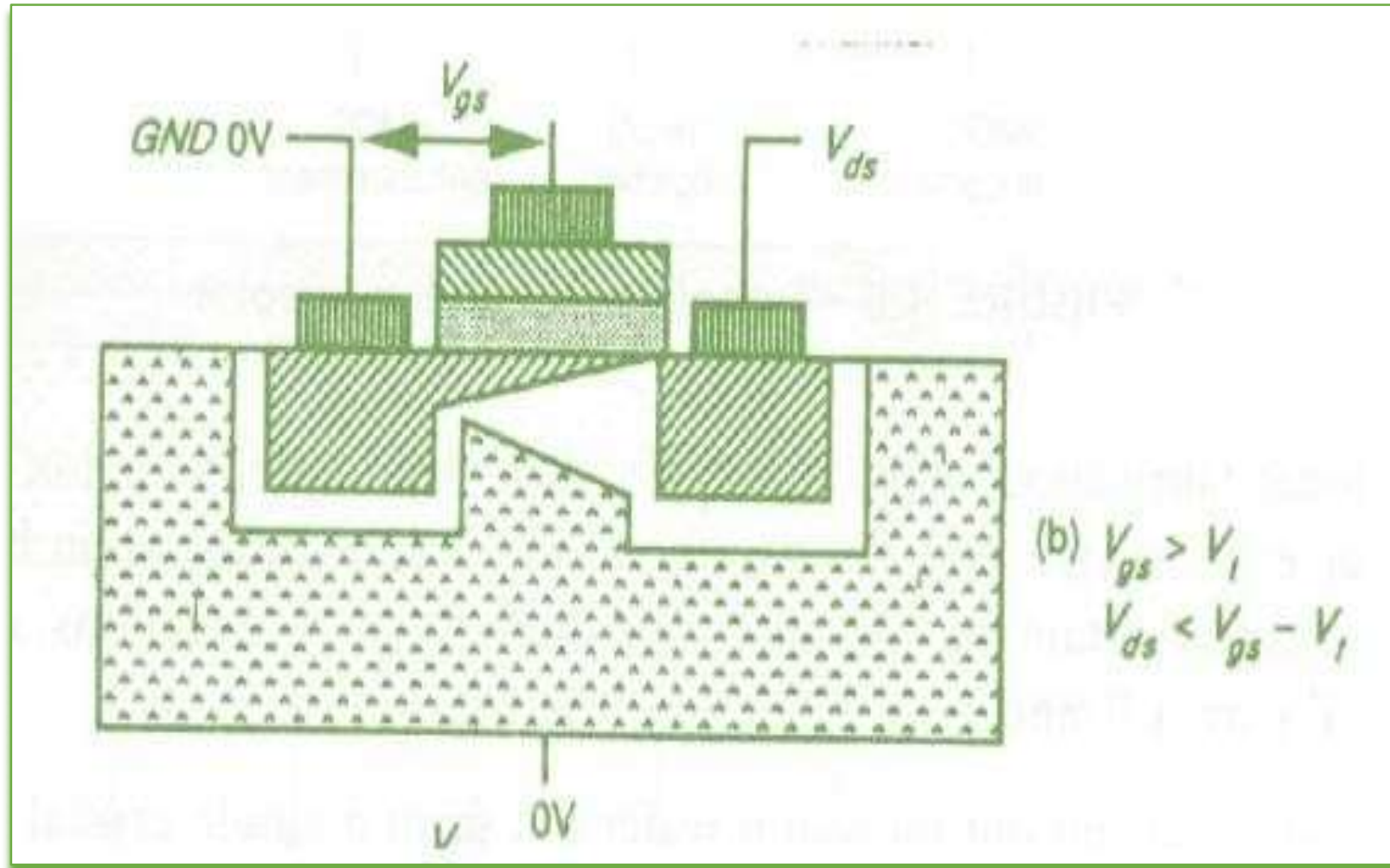


A) ENHANCEMENT MODE NO CURRENT FLOWS



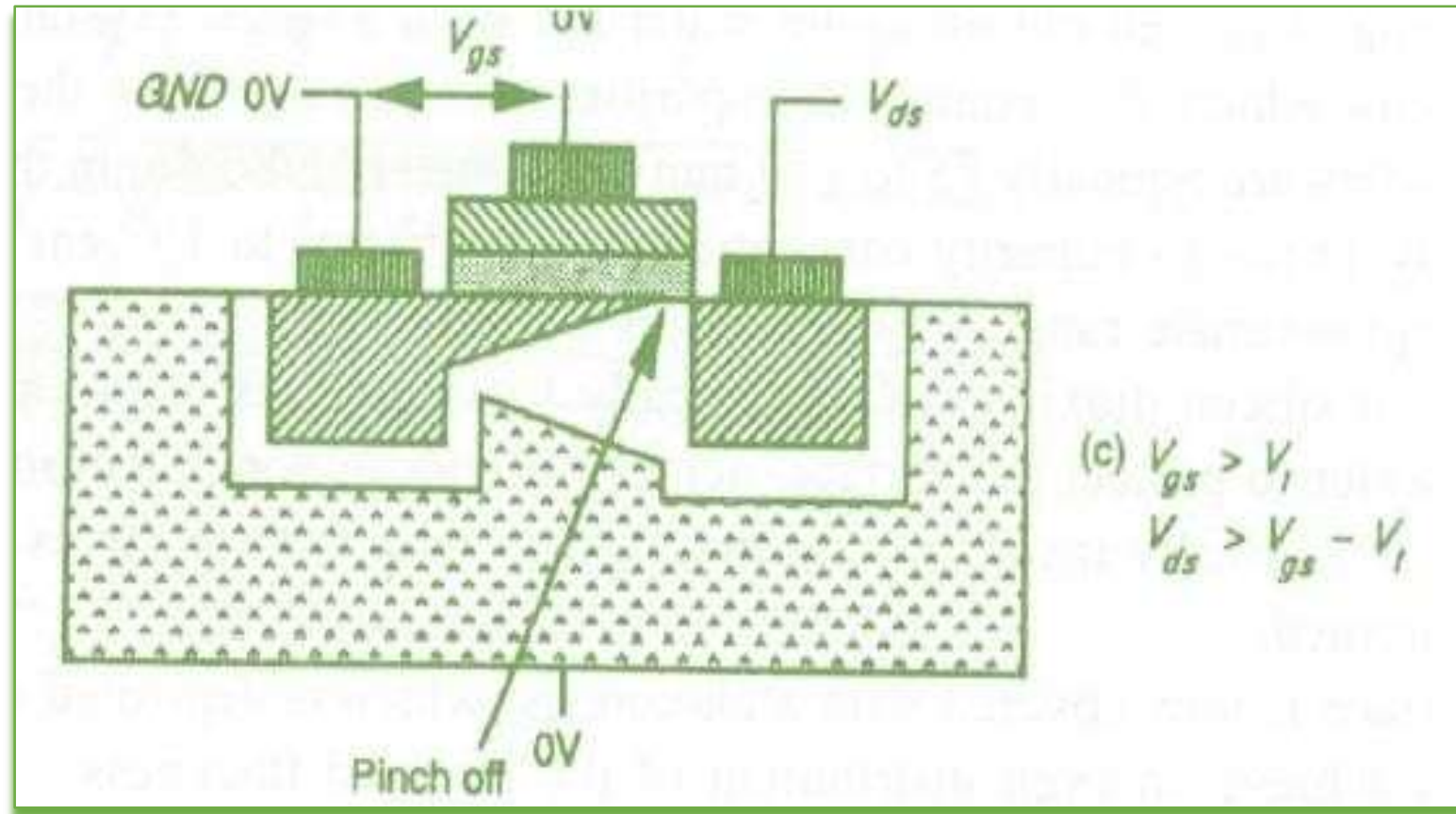


B) NON SATURATION



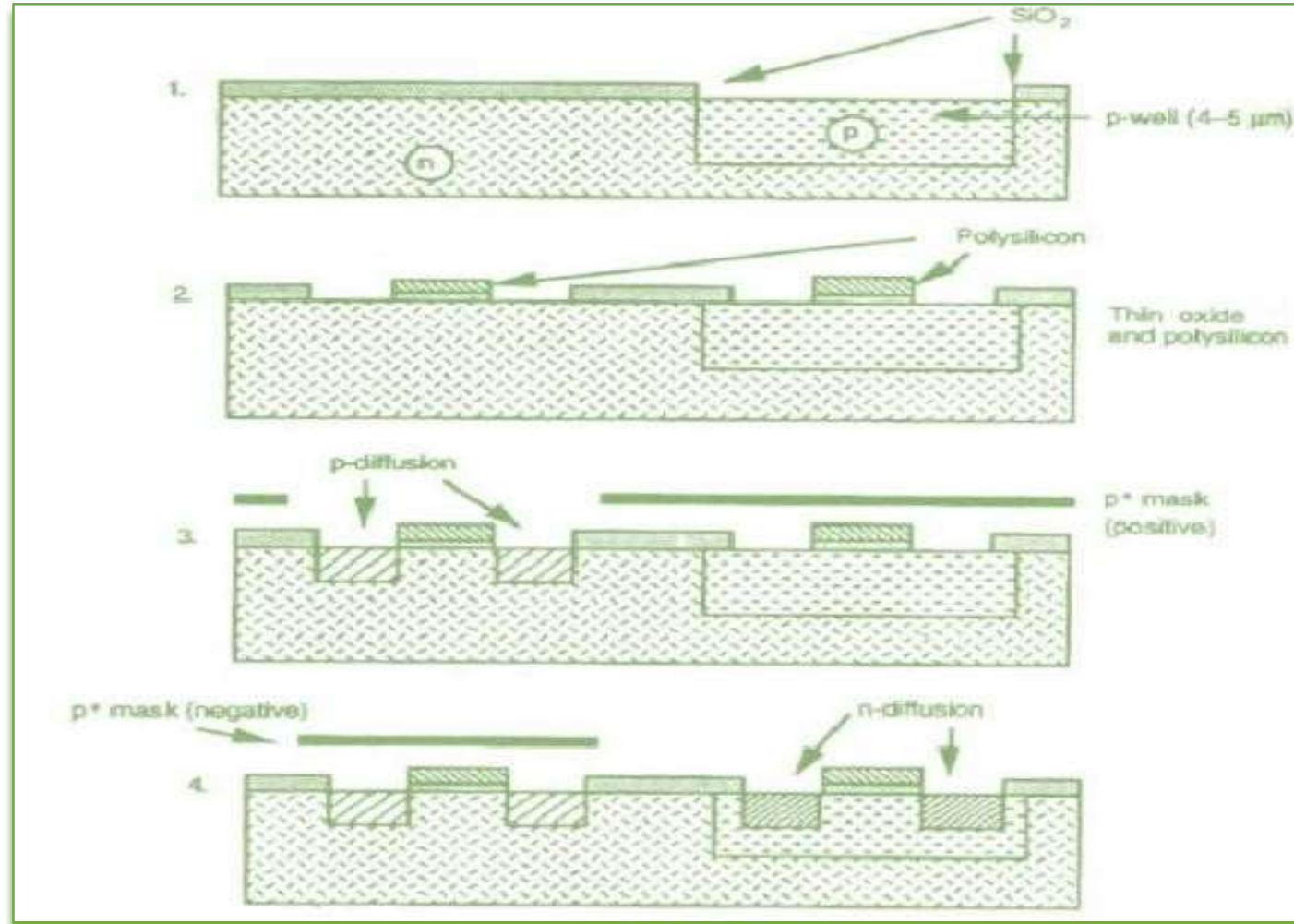


C) SATURATION-CONSTANT CURRENT





P-WELL PROCESS-MASKS LEVELS





P-WELL PROCESS-MASKS LEVELS

1-p-well diffusion defined

2defines thinox, those areas where the thickox is stripped & thinox grown to accomodate p & n transistor & wires

3 pattern poly silicon layer-CVD

4P+ MASK(+) –define all p diffusion areas(anded with mask2)



P-WELL PROCESS-MASKS LEVELS

5P+ MASK(-) –define n-type diffusion (anded with mask2)

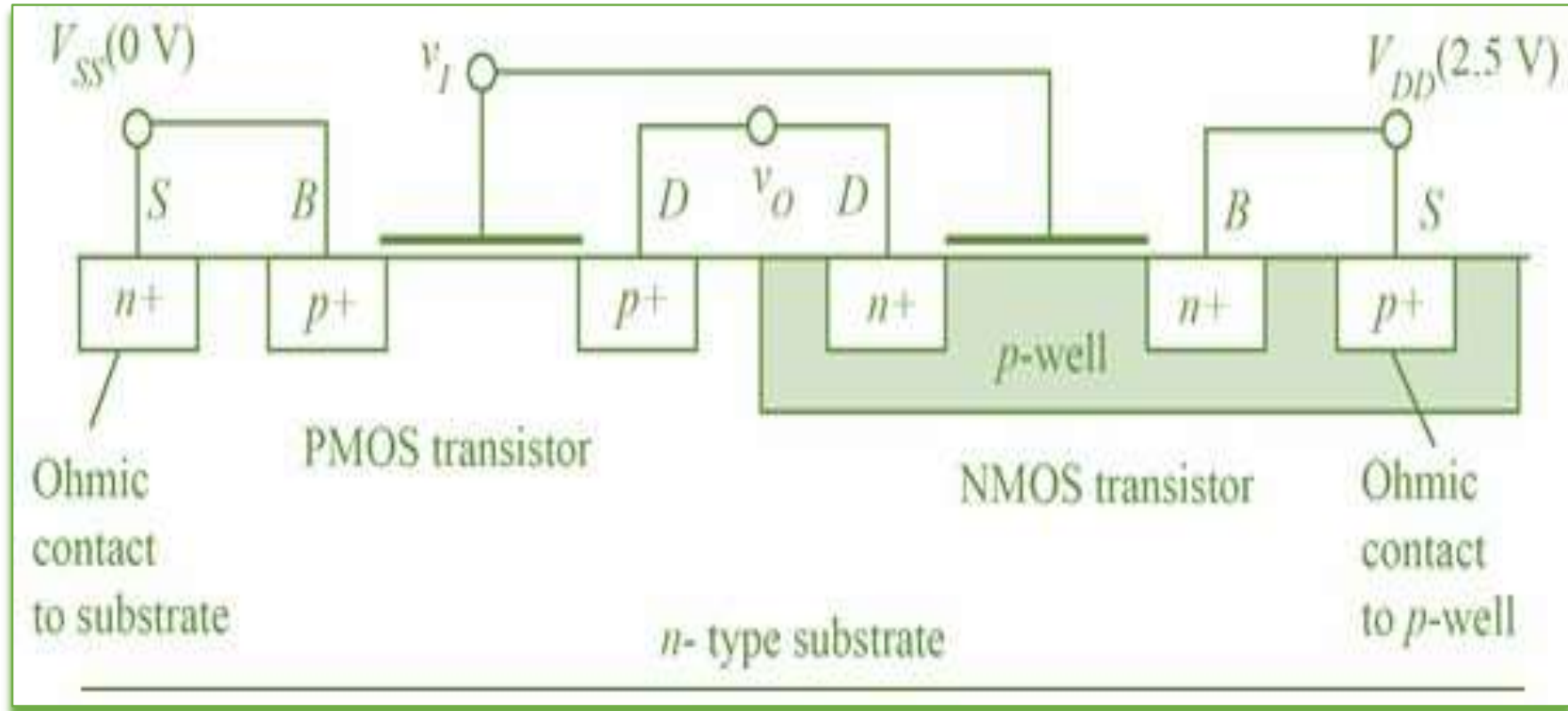
6 define contact cuts

7 define metal layer pattern

8 overall passivation (over glass) and opening for access to bonding pads



CMOS-P-WELL INVERTER





ASSESSMENT

1. $\mu_n = \text{-----} \mu_p \rightarrow$ n / p MOS is speed

$$V_{td} < \text{-----} V_{dd}$$

2. p-well Mask levels—1,3,5,7-----?

3. p-well Mask levels—2,4,6,8---?

4. Non Saturation $V_{ds} = ??$

5. Define Pinch off?



SUMMARY

THANK YOU...